



50V - 1.5A QUAD DARLINGTON SWITCHES

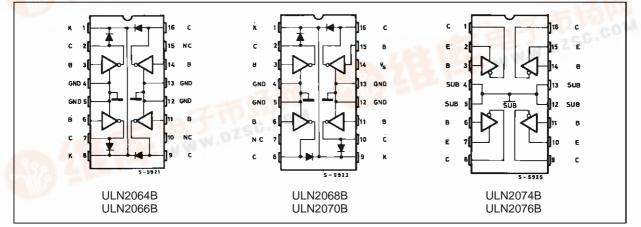
- OUTPUT CURRENT TO 1.5 A EACH DAR-LINGTON
- MINIMUM BREAKDOWN 50 V
- SUSTAINING VOLTAGE AT LEAST 35 V
- INTEGRAL SUPPRESSION DIODES (ULN2064B, ULN2066B, ULN2068B and ULN2070B)
- ISOLATED DARLINGTON PINOUT (ULN2074B, ULN2076B)
- VERSIONS COMPATIBLE WITH ALL POPU-LAR LOGIC FAMILIES

DESCRIPTION

Designed to interface logic to a wide variety of high current, high voltageloads, these devices each contain four NPN darlington switches delivering up to 1.5 A with a specified minimum breakdown of 50 V and a sustaining voltage of 35 V measured at 100 mA. The ULN2064B, ULN2066B, ULN2068B and ULN2070B contain integral suppression diodes for inductive loads have common emitters. The ULN2074B and ULN2076B feature isolated darlington pinouts and are intended for applications such as emitter follower configurations. Inputs of the ULN2064B, ULN2068B and ULN2074B are compatible with popular 5 V logic families and the ULN2066B and ULN2076B are compatible with 6-15 V CMOS and PMOS. Types ULN2068B and ULN2070Binclude a predriver stage to reduce loading on the control logic.

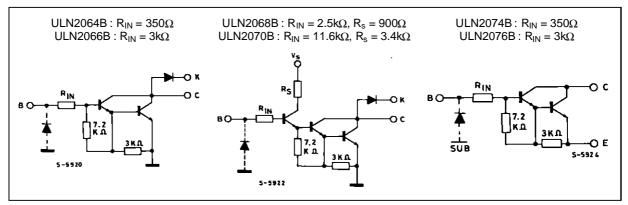
PIN CONNECTIONS AND ORDER CODES







SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol		Parameter	Value	Unit
V _{CEX}	Output Voltage		50	V
V _{CE(sus)}	Output Sustaining	Voltage	35	V
Ι _Ο	Output Current		1.75	A
Vi	Input Voltage	for ULN2066B – 2070B - 2074B - 2076B for ULN2064B – 2068B	30 15	V V
lı	Input Current		25	mA
Vs	Supply Voltage	for ULN2068B for ULN2070B	10 20	V V
Ptot	Power Dissipation	at T _{pins} = 90 °C at T _{amb} = 70 °C	4.3 1	W W
T _{amb}	Operating Ambient Temperature Range		– 20 to 85	°C
T _{stg}	Storage Temperatu	ire	– 55 to 150	°C

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	Fig.
I _{CEX}	Output Leakage Current				100 500	μΑ μΑ	1
V _{CE(sus)}	Collector-emitter Sustaining Voltage	$I_{C} = 100 \text{mA}, V_{i} = 0.4 \text{V}$	35			V	2
V _{CE(sat)}	Collector-emitter Saturation Voltage	$\begin{array}{ll} I_{C} = 500 \text{mA} & I_{B} = 625 \mu \text{A} \\ I_{C} = 750 \text{mA} & I_{B} = 935 \mu \text{A} \\ I_{C} = 1 \text{A} & I_{B} = 1.25 \text{mA} \\ I_{C} = 1.25 \text{A} & I_{B} = 2 \text{mA} \end{array}$			1.1 1.2 1.3 1.4	V V V V	3 3 3 3 3
l _{i(on)}	Input Current	for ULN2064B and ULN2074B $V_i = 2.4V$ $V_i = 3.75V$ for ULN2066B and ULN2076B $V_i = 5V$ $V_i = 12V$ for ULN2068B $V_i = 2.75V$ $V_i = 3.75V$ for ULN2070B $V_i = 5V$ $V_i = 12V$	1.4 3.3 0.6 1.7		4.3 9.6 1.8 5.2 0.55 1.0 0.4 1.25	mA mA mA mA mA mA	4 4 4 4 4 4 4 4



Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	Fig.
V _{i(on)}	Input Voltage	V _{CE} = 2V, I _C = 1A ULN2064B, ULN2074B ULN2066B, ULN2076B V _{CE} = 2V, I _C = 1.5A ULN2064B, ULN2074B ULN2066B, ULN2076B ULN2068B ULN2070B			2 6.5 2.5 10 2.75 5	V V V V V	55 55555
ls	Supply Current	for ULN2068B $I_{C} = 500$ mA, $V_{i} = 2.75V$ for ULN2070B $I_{C} = 500$ mA, $V_{i} = 5V$			6 4.5	mA mA	8 8
t _{PLH}	Turn-on Delay Time	0.5 V _i to 0.5 V _o			1	μs	
t _{PHL}	Turn-off Delay Time	0.5 V_i to 0.5 V_o			1.5	μs	
I _R	Clamp Diode Leakage Current	for ULN2064B-ULN2066B and ULN2068B-ULN2070B $V_R = 50 V$ $T_{amb} = 25^{\circ}C$ $T_{amb} = 70^{\circ}C$			50 100	μΑ μΑ	6
VF	Clamp Diode Forward Voltage	for ULN2064B-ULN2066B and ULN2068B-ULN2070B I _F = 1 A I _F = 1.5 A			1.75 2	V V	7

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}C$ unless otherwise specified) (continued)

Notes : 1. Input voltage is with reference to the substrate (no connection to any other pins) for the ULN2074B and ULN2076B reference is ground for all other types.
Input current may be limited by maximum allowable input voltage.

TEST CIRCUITS

Figure 1.

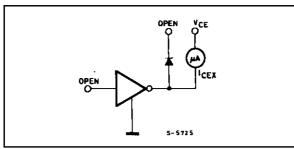


Figure 3.

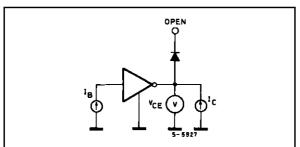
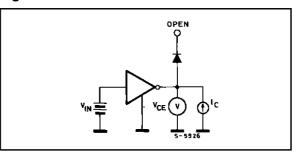


Figure 2.





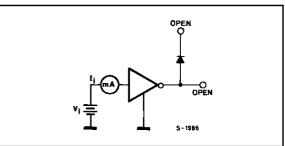




Figure 5.

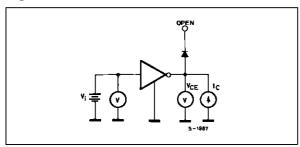


Figure 7.

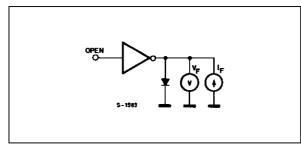


Figure 9 : Input Current as a Function of Input Voltage.

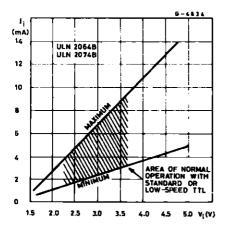


Figure 11 : Collector Current as a Function of Input Current.

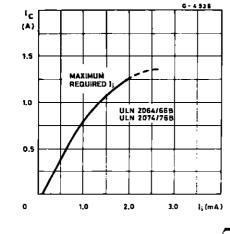


Figure 6.

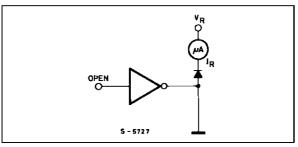


Figure 8.

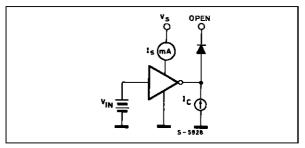
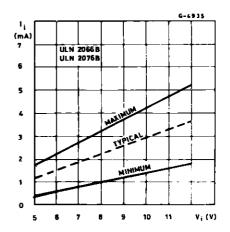
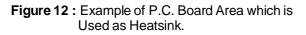


Figure 10 : Input Current as a Function of Input Voltage.



MOUNTING INSTRUCTIONS

The R_{th j-amb} can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (Fig. 12) or to an external heatsink (Fig. 13). The diagram of Figure 14 shows the maximum dissipable power P_{tot} and the R_{th j-amb} as a function of the side " α " of two equal square copper areas having a thickness of 35 μ (1.4 mils).



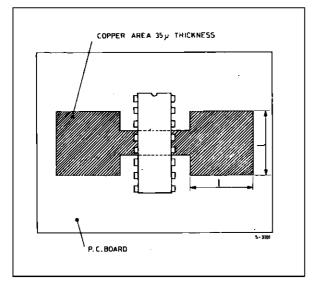
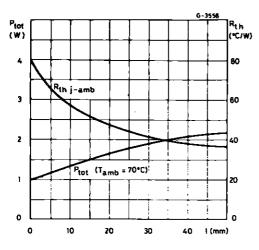


Figure 14 : Maximum Dissipable Power and Junction to Ambient Thermal Resistance vs. Side " α ".



During soldering the pins temperature must not exceed 260 $^{\circ}$ C and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 13 : External Heatsink Mounting Example.

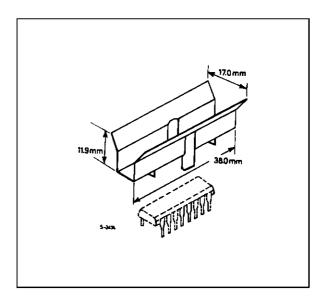
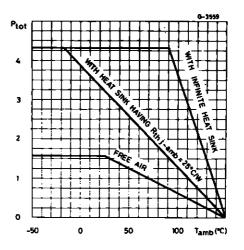


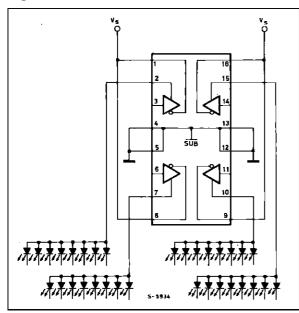
Figure 15 : Maximum Allowable Power Dissipation vs. Ambient Temperature.





TYPICAL APPLICATIONS

Figure 16 : Common-anode LED Drivers.



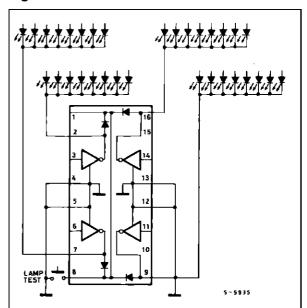
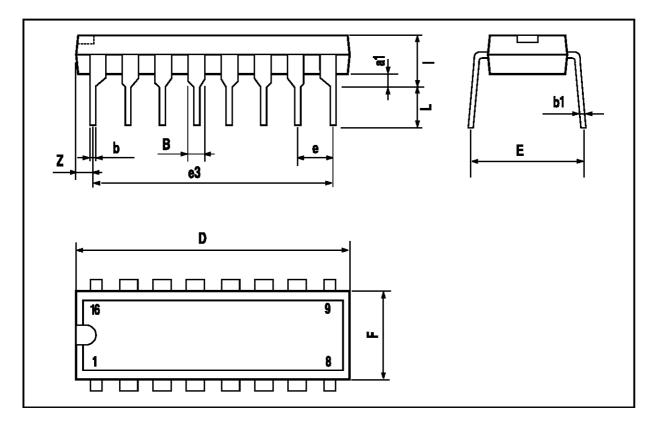


Figure 17 : Common-cathode LED Drivers.



DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
a1	0.51			0.020			
В	0.85		1.40	0.033		0.055	
b		0.50			0.020		
b1	0.38		0.50	0.015		0.020	
D			20.0			0.787	
E		8.80			0.346		
е		2.54			0.100		
e3		17.78			0.700		
F			7.10			0.280	
I			5.10			0.201	
L		3.30			0.130		
Z			1.27			0.050	

POWERDIP 16 PACKAGE MECHANICAL DATA





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